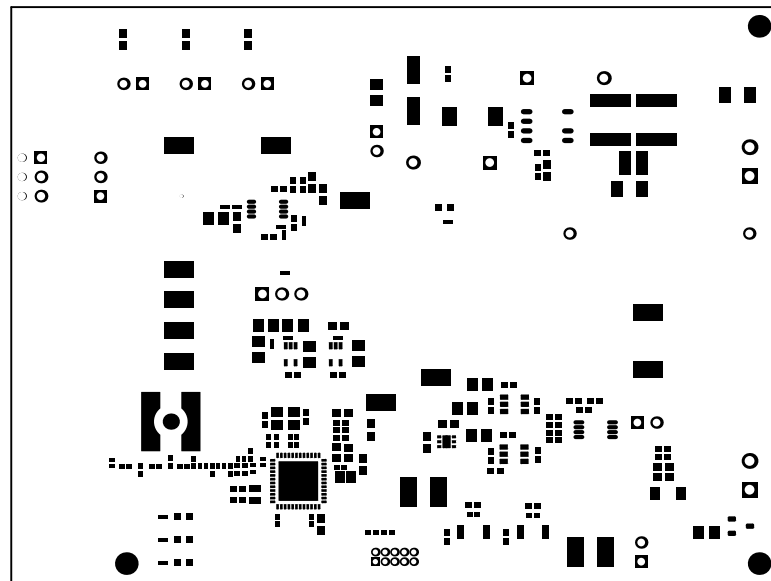
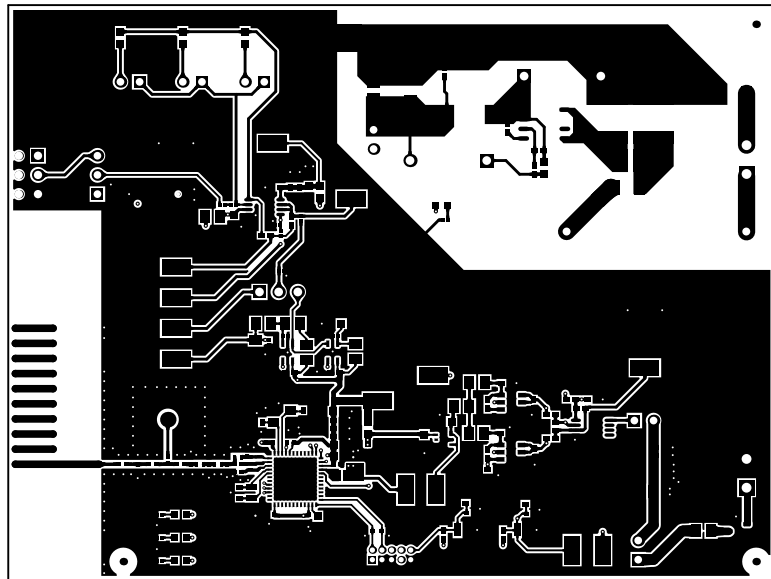


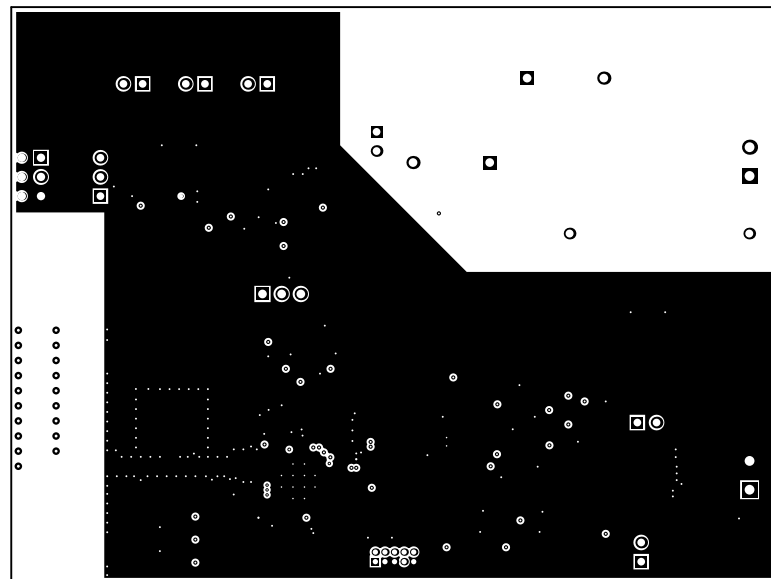
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01519	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #:	N/A	
PLOT NAME = Top Overlay	GENERATED	: 8/29/2017 2:04:45 PM	TEXAS INSTRUMENTS



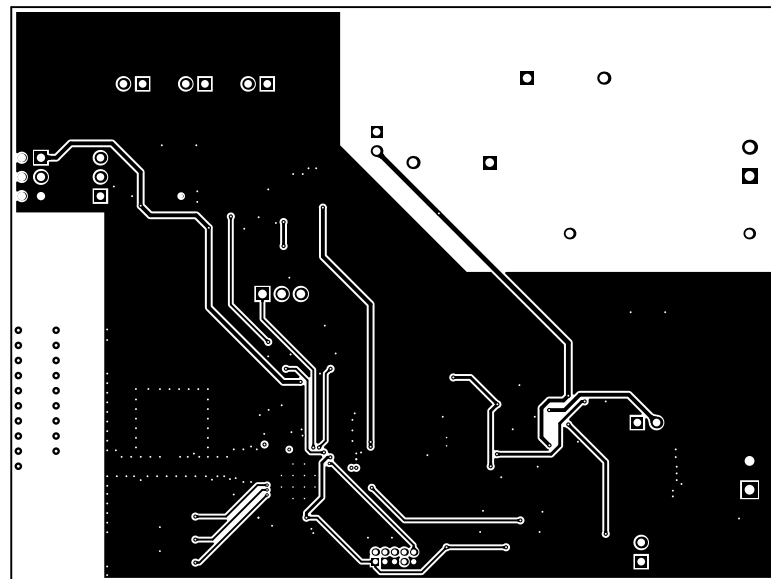
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01519	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 8/29/2017 2:04:45 PM	TEXAS INSTRUMENTS	



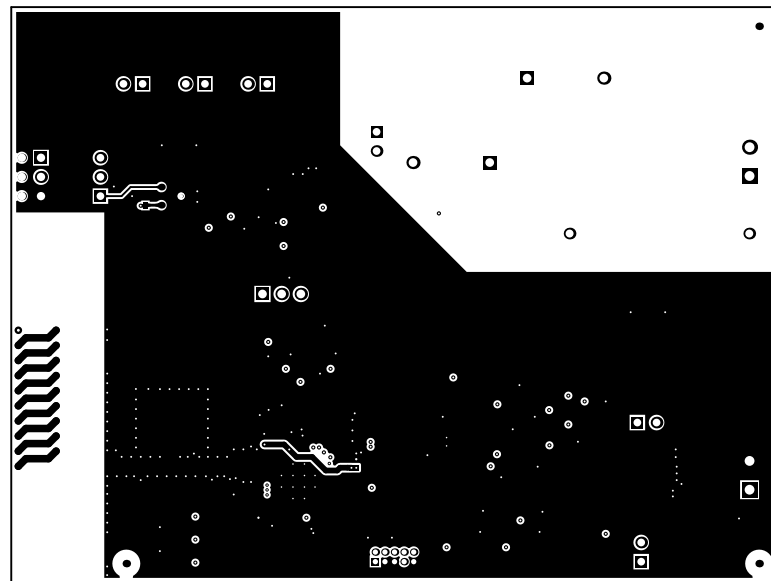
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01519	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 8/29/2017 2:04:46 PM	TEXAS INSTRUMENTS	



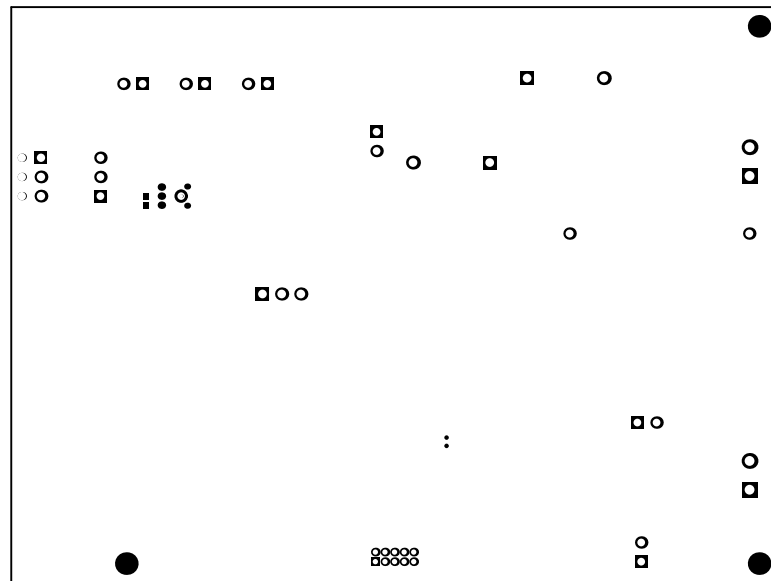
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01519	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 1	TID #: N/A		
PLOT NAME = Signal Layer 1	GENERATED : 8/29/2017 2:04:47 PM	TEXAS INSTRUMENTS	



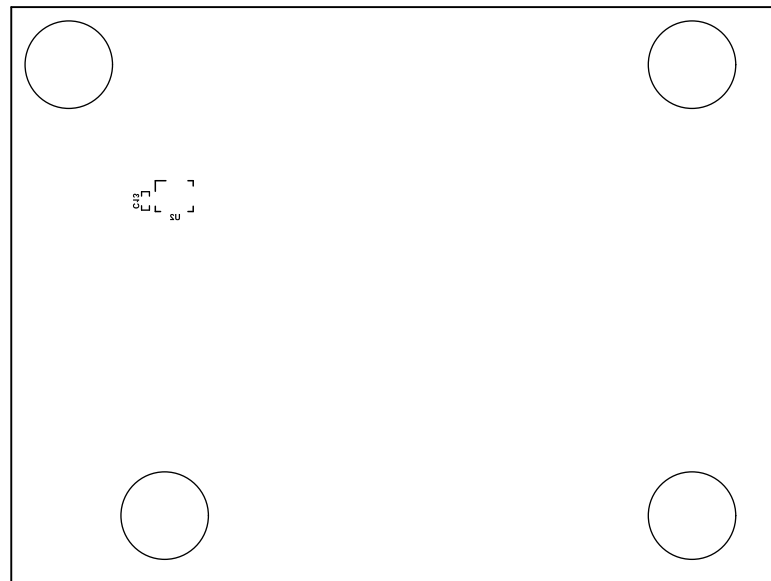
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01519	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 2	TID #: N/A		
PLOT NAME = Signal Layer 2	GENERATED : 8/29/2017 2:04:47 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01519	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 8/29/2017 2:04:48 PM	TEXAS INSTRUMENTS	



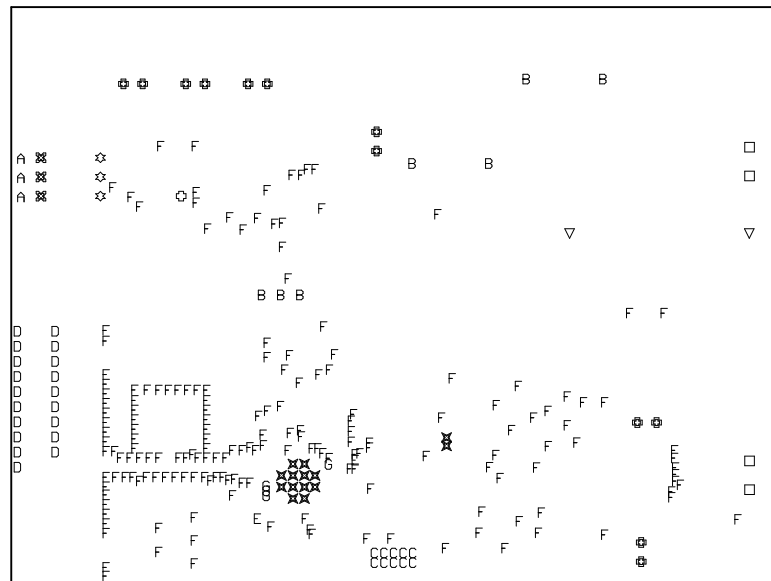
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01519	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 8/29/2017 2:04:48 PM	TEXAS INSTRUMENTS	



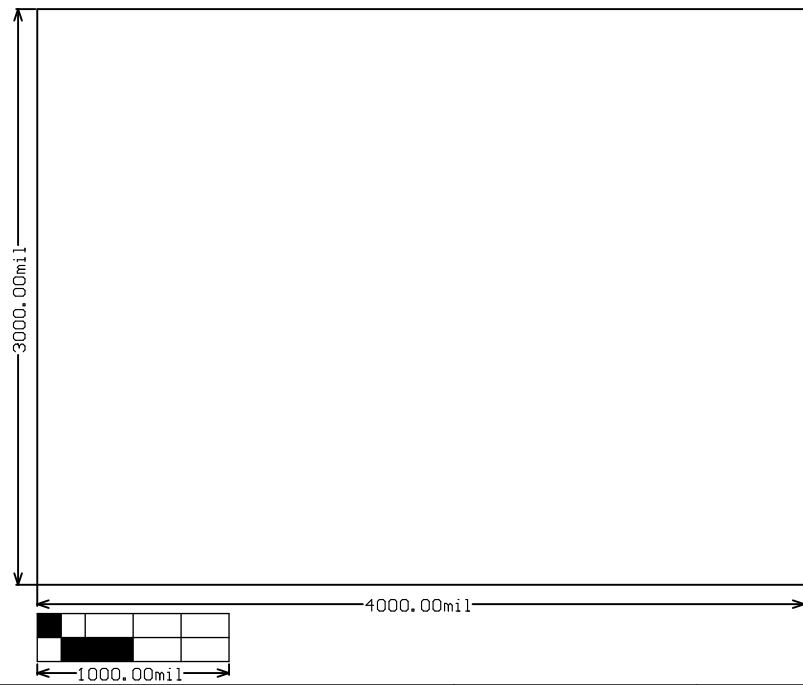
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01519	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 8/29/2017 2:04:49 PM	TEXAS INSTRUMENTS	



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
⊕	1	19.69mil (0.500mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c40hn50m40
E	2	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v61h30m0mx0
∇	2	41.34mil (1.050mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c155h105
⊗	3	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
A	3	43.31mil (1.100mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c110hn110m110
⊗	3	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
G	4	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v46h20m0mx0
□	4	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
B	7	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
C	10	27.56mil (0.700mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
⊕	12	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
⊗	14	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)
D	19	14.96mil (0.380mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v100h38m0
F	179	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)
	263 Total							



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01519	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 8/29/2017 2:04:50 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01519	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 8/29/2017 2:04:50 PM	TEXAS INSTRUMENTS	

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